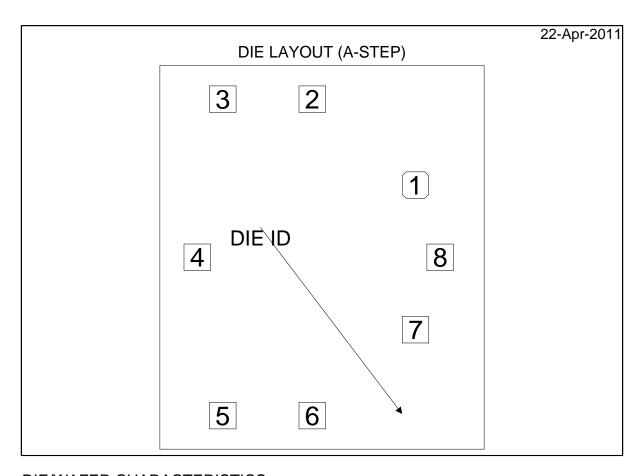


LMH6715-MDR DUAL WIDEBAND VIDEO OP AMP



DIE/WAFER CHARACTERISTICS

DIL/WAI LIX CHANA	CILINISTICS				
Fabrication Attributes		General Die Information			
Physical Die	LMH6715A	Bond Pad Opening 77.00µm x 77.00			
Identification		Size (min)			
Die Step	А	Bond Pad Metalization	0.5%CU		
Physical Attributes		Passivation	PECVDOX NITRIDE		
Wafer Diameter	152.4mm	Back Side Metal	BAREBACK		
Die Size (Drawn)	942.340µm x	Back Side Connection	Floating		
	1115.060µm				
	37.1mils x 43.9mils				
Thickness	304.8µm Nominal				
Min Pitch	259.90µm				
Note: All values are round	ded to the nearest micron				
Special Assembly Require	ements:				



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Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		Χ	Υ	Χ		Υ
V out 1	1	271.70	209.90	77.00	Х	77.0
V inv 1	2	-28.30	459.70	77.00	Х	77.0
V non-inv 1	3	-288.20	459.70	77.00	Х	77.0
- VCC	4	-362.60	0.20	77.00	Х	77.0
V non-inv 2	5	-288.20	-460.10	77.00	Х	77.0
V inv 2	6	-28.30	-460.10	77.00	Х	77.0
V out 2	7	271.80	-210.40	77.00	Х	77.0
+ VCC	8	343.30	0.10	77.00	Х	77.0



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